

Title (en)
DEVICE AND METHOD FOR TREATING ELECTROCONDUCTIVE ENDLESS MATERIAL

Title (de)
VORRICHTUNG UND VERFAHREN ZUR BEHANDLUNG VON ELEKTRISCH LEITFÄHIGEM ENDLOSMATERIAL

Title (fr)
PROCEDE ET DISPOSITIF POUR TRAITER UN MATERIAU CONTINU ELECTROCONDUCTEUR

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Application
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Abstract (en)
[origin: WO0050667A1] Disclosed is a device for treating electroconductive endless material (3) such as wire, especially copper wire. The inventive devices treats said material during the movement of the endless material and in the extension direction thereof and can be used for heating or annealing the endless material or for cleaning the surface thereof. The inventive device comprises a contact device (15) for electrically contacting the moved endless material (3) and an electrode arrangement (17) which is arranged at a distance from the endless material (3) and which at least partially encompasses the endless material. A gas discharge chamber (11) is arranged between the endless material (3) and the electrode arrangement (17) and is filled with a reaction gas. A voltage is impressed across the contact device (5) and the electrode arrangement (17) and in said gas discharge chamber (11). An electric gas discharge can thus be produced in order to treat the endless material (3).

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